

650V N-Channel MOSFET

FEATURES

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information					
Device	Package	Marking			
TMA4N65L	TO-220F	A4N65L			
TMP4N65L	TO-220	P4N65L			
TMU4N65L	TO-251	U4N65L			
TMD4N65L	TO-252	D4N65L			



Absolute Maximum Ratings $T_c = 25^{\circ}C$, unless otherwise noted							
Deveneder	Symbol	Value				11	
Parameter		TO-220F	TO-220	TO-251	TO-252	Unit	
Drain-Source Voltage ($V_{GS} = 0V$)	V _{DSS}	650			V		
Continuous Drain Current	I _D	3			A		
Pulsed Drain Current (note1)	I _{DM}	12				А	
Gate-Source Voltage	V _{GSS}	±30				V	
Single Pulse Avalanche Energy (note2)	E _{AS}	90			mJ		
Avalanche Current (note1)	I _{AR}	3			А		
Repetitive Avalanche Energy (note1)	E _{AR}	10			mJ		
Power Dissipation ($T_c = 25^{\circ}C$)	P _D	30 45			W		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150			°C		

Thermal Resistance							
Beremeter	Symbol	Value				l lm it	
Parameter		TO-220F	TO-220	TO-251	TO-252	Unit	
Thermal Resistance, Junction-to-Case	R _{thJC}	4.1	2.8		°C/W		
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62.5	60				



Specifications $T_J = 25^{\circ}C$, unless otherwise noted									
Densmalar		T	Value						
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit «.			
Static									
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250 \mu A$	650			V			
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA			
Gate-Source Leakage	I _{GSS}	V_{GS} = $\pm 30V$			±100	nA			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3.0		4.0	V			
Drain-Source On-Resistance (Note3)	R _{DS(on)}	V _{GS} = 10V, I _D = 1.5A		2.7	3.2	Ω			
Dynamic									
Input Capacitance	C _{iss}			462		pF			
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 25V,$		54.2					
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		8.8					
Total Gate Charge	Q _g			13.5		nC			
Gate-Source Charge	Q _{gs}	$V_{DD} = 520V, I_D = 3.0A, V_{GS} = 10V$		2					
Gate-Drain Charge	Q _{gd}			6					
Turn-on Delay Time	t _{d(on)}			10		ns			
Turn-on Rise Time	t _r	V 400V I 3.0A		25					
Turn-off Delay Time	t _{d(off)}	$V_{\text{DD}} = 400\text{V}, \text{I}_{\text{D}} = 3.0\text{A},$ $\text{R}_{\text{G}} = 25 \ \Omega$		40					
Turn-off Fall Time	t _f			52					
Drain-Source Body Diode Character	istics								
Continuous Body Diode Current	I _S	T 0500			3	A			
Pulsed Diode Forward Current	I _{SM}	T _C = 25 °C			12				
Body Diode Voltage	V _{SD}	T _J = 25°C, I _{SD} = 3.0A, V _{GS} = 0V			1.4	V			
Reverse Recovery Time	t _{rr}	V _{GS} = 0V,I _S = 3.0A,		220		ns			
Reverse Recovery Charge	Q _{rr}	$di_{\rm F}/dt = 100A /\mu s$		3		μC			

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 3A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 °C
- 3. Pulse Test: Pulse width \leq 300µs, Duty Cycle \leq 1%

TMA4N65L,TMU4N65L,TMD4N65L, TMP4N65L



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Figure 2. Body Diode Forward Voltage





















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Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted









Figure B: Resistive Switching Test Circuit and Waveform



Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-220F







TO-220





TO-251





TO-252





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